ABSTRACT DEADLINE EXTENDED: APRIL 16, 2010

IMAPS 2010 Symposium - Call for Papers

Bringing Together the Entire Microelectronics Supply Chain!

Raleigh Convention Center, Raleigh, North Carolina - USA

October 31 - November 4, 2010

The 43rd International Symposium on Microelectronics will be held at the Raleigh Convention Center, Research Triangle, North Carolina, USA, and is being sponsored by the International Microelectronics And Packaging Society (IMAPS). The IMAPS Technical Committee seeks original papers that present progress on technologies "between the chip and the system." The 43rd Symposium on Microelectronics will cover four tiers of electronics: Industry, Systems & Applications, Design, and Materials & Process. Abstracts should highlight the major contributions of the work in one or more of these four areas. All abstracts submitted must represent original, previously unpublished work.

General Chair:
David Seeger, IBM Corporation
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Technical Chair:
Sara Paisner, LORD Corporation
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Technical Co-Chairs:

Europe: Georg Meyer-Berg
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Asia: Jin Yu
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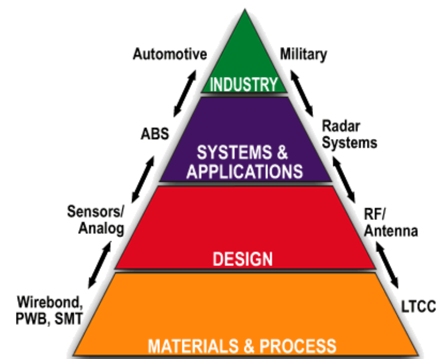

Planned Sessions Include

Industry

- Consumer, Portable, and Wireless
- Biomedical
- Telecom
- Defense and Security
- Computing and Gaming
- Automotive, Industrial, Harsh Environment Electronics Applications
- Solar and Alternative Energy

3D Integration and Packaging Technology Track

- 3D System Integration
- 3D Packaging Approaches
- 3D Processing Technology
- 3D Equipment and Materials Advances
- 3D Simulation and Modeling

Systems & Applications

- Thermal Management
- Power Management
- Cost Reduction, Outsourcing and Supply Chain Management
- Electromagnetic Interference (EMI)
- Sensors and Nano Packaging
- Emerging Technologies
- System Packaging
- Microwave & RF Applications
- Electrostatic Discharge (ESD) Protection
- Photonic / Optoelectronic Packaging
- Packaging for Extreme Environments
- MEMS Packaging
- LED Packaging
- Packaging of Compound Semiconductor Devices

Design

- Electrical Modeling, Signal & Power Integrity
- High Performance Interconnects and Boards
- Embedded and Integrated Passives
- Wafer Level Packaging / CSP
- Advanced Materials

Materials and Process

- Flip-Chip and Wafer Bumping Processes and Reliability
- Underfill/Encapsulants, and Adhesives
- Pb-Free Solder Materials, RoHS, Processes, and Reliability
- Design for Reliability
- Package Reliability Testing
- Wirebonding and Stud Bumping
- Ceramic and LTCC Packaging
- Substrate Materials and Technology
- Printed Electronics
- Ultra Low-k Packaging
- Uses of Precious Metals in Microelectronics

Translated (Invited Speakers Only)

- Japanese (Japanese to English translation)
- Chinese (Chinese to English translation)

Poster Session (Interactive Forum)

Outstanding papers that do not fit in planned or created sessions will be considered for the interactive poster session.

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Visit www.imaps2010.org for more information!

Please send your 250-300 word abstract **electronically only** using the on-line submittal form at: **www.imaps.org/abstracts.htm**

Abstract Cut-off Date Extended: April 16, 2010 | **Notice of Acceptance: May 7, 2010** | **Final Manuscript Due: August 27, 2010**

All Speakers are required to pay a reduced registration fee in recognition of their contribution to the event.

Cash Awards Offered: $2000 for one Best Paper of Symposium; $500 each for two Outstanding Papers of Symposium.

Accepted papers may be considered for publication in the IMAPS Journal of Microelectronics and Electronic Packaging (http://www.imaps.org/jmep/index.htm).

If you need assistance with the on-line submission form, please email Jackki Morris-Joyner (jmorris@imaps.org) or call 305-382-8433.

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